

## TS5A3159-Q1 1Ω SPDT 模拟开关

### 1 特性

- 适用于汽车电子 应用
- 具有符合 AEC-Q100 的下列结果：
  - 器件温度 1 级：-40℃ 至 +125℃ 的环境运行温度范围
  - 器件人体模型 (HBM) 静电放电 (ESD) 分类等级 2
  - 器件组件充电模式 (CDM) ESD 分类等级 C4B
- 额定的先断后合开关
- 低导通状态电阻 (1Ω)
- 控制输入可承受 5V 电压
- 低电荷注入
- 出色的导通电阻匹配
- 低总谐波失真
- 1.65V 至 5.5V 单电源运行

### 2 应用范围

- 汽车信息娱乐和仪表盘
- 车身电子装置和照明

### 3 说明

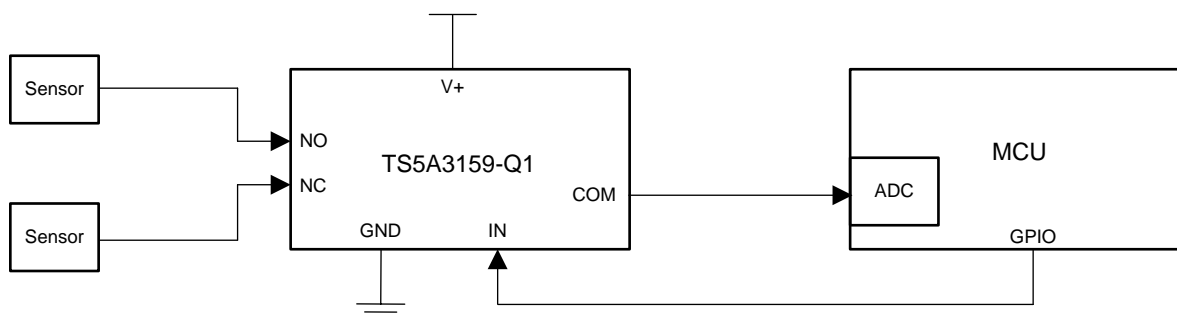
TS5A3159-Q1 是一款单刀双掷 (SPDT) 模拟开关，工作电压范围设计为 1.65V 至 5.5V。该器件具有低导通状态电阻和出色的通道间导通状态电阻匹配，其先断后合的特性可防止信号在路径间传输时出现失真。此器件具有出色的总谐波失真 (THD) 性能并且能耗极低。这些功能使得这款器件适合于便携式音频应用。

#### 器件信息<sup>(1)</sup>

器件型号	封装	封装尺寸 (标称值)
TS5A3159-Q1	SOT-23 (6)	2.90mm x 4.00mm

(1) 如需了解所有可用封装，请参见数据表末尾的可订购产品附录。

#### 选择器应用



## 目录

1 特性 .....	1	8.2 Functional Block Diagram .....	17
2 应用范围 .....	1	8.3 Feature Description .....	17
3 说明 .....	1	8.4 Device Functional Modes .....	17
4 修订历史记录 .....	2	<b>9 Applications and Implementation .....</b>	<b>18</b>
<b>5 Pin Configuration and Functions .....</b>	<b>4</b>	9.1 Application Information .....	18
<b>6 Specifications .....</b>	<b>4</b>	9.2 Typical Application .....	18
6.1 Absolute Maximum Ratings .....	4	<b>10 Power Supply Recommendations .....</b>	<b>19</b>
6.2 ESD Ratings .....	4	<b>11 Layout .....</b>	<b>19</b>
6.3 Recommended Operating Conditions .....	5	11.1 Layout Guidelines .....	19
6.4 Thermal Information .....	5	11.2 Layout Example .....	19
6.5 Electrical Characteristics for 5-V Supply .....	5	<b>12 器件和文档支持 .....</b>	<b>20</b>
6.6 Electrical Characteristics for 3.3-V Supply .....	6	12.1 文档支持 .....	20
6.7 Electrical Characteristics For 2.5-V Supply .....	8	12.2 接收文档更新通知 .....	20
6.8 Electrical Characteristics For 1.8-V Supply .....	9	12.3 社区资源 .....	20
6.9 Typical Characteristics .....	10	12.4 商标 .....	20
<b>7 Parameter Measurement Information .....</b>	<b>12</b>	12.5 静电放电警告 .....	20
<b>8 Detailed Description .....</b>	<b>17</b>	12.6 Glossary .....	20
8.1 Overview .....	17	<b>13 机械、封装和可订购信息 .....</b>	<b>20</b>

## 4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Revision B (October 2015) to Revision C	Page
• Changed I/O for $V_{+}$ from I to — .....	4
• Added $V_{COM}$ to Analog voltage, Analog port diode current, and ON-state switch current .....	4
• Added Junction temperature, $T_J$ to <i>Absolute Maximum Ratings</i> .....	4
• Changed MIN value for $V_{+}$ from 1.8 to 1.65 and MAX value from 5 to 5.5 .....	5
• Changed MAX value for $I_{IN}$ from 5 to 5.5 .....	5
• Changed MAX value for $I_{NO}$ , $I_{NC}$ , $I_{COM}$ from 5 to $V_{+}$ .....	5
• Added $V_{IL}$ MAX value 0.6 and deleted TYP value 0.6 .....	7
• 已添加 接收文档更新通知部分 .....	20

Changes from Revision A (December 2012) to Revision B	Page
• Added ESD Ratings table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	4

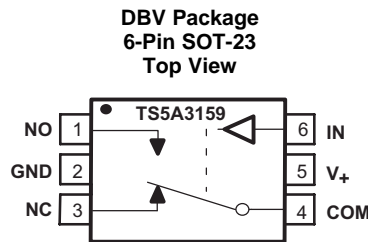
Changes from Original (November, 2012) to Revision A	Page
• 器件从预览变为生产 .....	1
• Changed $r_{on}$ max values from 1.1 to 1.3 .....	5
• Changed $I_{NC(OFF)}$ , $I_{NO(OFF)}$ min and max values for 25°C from –2 and 2 to –6 and 6, respectively. Changed min and max values for Full from –20 and 20 to –150 and 150, respectively .....	5
• Changed $I_{NC(ON)}$ , $I_{NO(ON)}$ min and max values for 25°C from –4 and 4 to –6 and 6, respectively. Changed min and max values for Full from –40 and 40 to –150 and 150, respectively .....	5
• Changed $I_{COM(ON)}$ min and max values for 25°C from –4 and 4 to –8 and 8, respectively. Changed min and max values for Full from –40 and 40 to –150 and 150, respectively. ....	5
• Inserted 25°C above Full in $T_A$ column and inserted 0.5 $\mu$ A max value for $I_{+}$ .....	6

---

• Changed max values for $r_{peak}$ from 2.1 to 2.2.....	6
• Changed max values for $r_{on}$ from 1.5 to 1.8. ....	6
• Added 25°C to $T_A$ column and added 0.5 max value to $I_+$ .....	7
• Changed $r_{peak}$ max values from 2.7 to 2.9.....	8
• Changed $r_{on}$ max values from 2 to 2.3. ....	8
• Added 25°C to $T_A$ column and added 0.5 max value to $I_+$ .....	8
• Changed $r_{peak}$ max values from 4.9 to 5.2.....	9
• Changed $r_{on}$ max values from 3.2 to 3.5. ....	9
• Added 25°C to $T_A$ column and added 0.5 max value to $I_+$ .....	9
• Changed ON-state resistance from 1.1 to 1.3 $\Omega$ .....	17
• Changd leakage current from $\pm 20$ nA to $\pm 6$ nA.....	17

---

## 5 Pin Configuration and Functions



**Pin Functions**

PIN		I/O	DESCRIPTION
NO.	NAME		
1	NO	I/O	Normally-open terminal
2	GND	—	Digital ground
3	NC	I/O	Normally-closed terminal
4	COM	I/O	Common terminal
5	V <sub>+</sub>	—	Power supply
6	IN	I	Digital control pin to connect COM terminal to NO or NC terminals

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT	
V <sub>+</sub>	Supply voltage <sup>(2)</sup>	-0.5	6.5	V	
V <sub>NO</sub> , V <sub>NC</sub> , V <sub>COM</sub>	Analog voltage <sup>(2)(3)(4)</sup>	-0.5	V <sub>+</sub> + 0.5	V	
I <sub>I/O</sub>	Analog port diode current	V <sub>NO</sub> , V <sub>NC</sub> , V <sub>COM</sub> < 0 or V <sub>NO</sub> , V <sub>NC</sub> , V <sub>COM</sub> > V <sub>+</sub>		±50	mA
I <sub>NO</sub> , I <sub>NC</sub> , I <sub>COM</sub>	ON-state switch current	V <sub>NO</sub> , V <sub>NC</sub> , V <sub>COM</sub> = 0 to V <sub>+</sub>		±200	mA
	ON-state peak switch current <sup>(5)</sup>			±400	mA
V <sub>IN</sub>	Digital input voltage range <sup>(2)(3)</sup>	-0.5	6.5	V	
I <sub>IK</sub>	Digital input clamp current	V <sub>IN</sub> < 0		-50	mA
	Continuous current through V <sub>+</sub> or GND			±100	mA
T <sub>J</sub>	Junction temperature			150	°C
T <sub>stg</sub>	Storage temperature	-65	150	°C	

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground, unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4) This value is limited to 5.5 V maximum.
- (5) Pulse at 1 ms duration < 10% duty cycle.

### 6.2 ESD Ratings

		VALUE	UNIT	
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±2000	
		Charged device model (CDM), per AEC Q100-011	Corner pins (NO, NC, IN, and COM)	±750
			Other pins	±500

- (1) AEC Q100-002 indicates HBM stressing is done in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
V+	1.65	5.5	V
IN	0	5.5	V
NO, NC, COM	0	V+	V

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TS5A3159-Q1	UNIT
		DBV (SOT-23)	
		6 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	192.9	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	133.3	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	37.6	°C/W
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	38.9	°C/W
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	37.1	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

### 6.5 Electrical Characteristics for 5-V Supply

V<sub>+</sub> = 4.5 V to 5.5 V and T<sub>A</sub> = -40°C to +125°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT		
<b>ANALOG SWITCH</b>									
V <sub>COM</sub> , V <sub>NO</sub> , V <sub>NC</sub>	Analog signal range			0		V <sub>+</sub>	V		
r <sub>peak</sub>	Peak ON resistance	0 ≤ V <sub>NO</sub> or V <sub>NC</sub> ≤ V <sub>+</sub> , I <sub>COM</sub> = -30 mA	Switch ON, See <a href="#">Figure 11</a>	25°C	4.5 V	1	1.5	Ω	
			Full			1.5			
r <sub>on</sub>	ON-state resistance	V <sub>NO</sub> or V <sub>NC</sub> = 2.5 V, I <sub>COM</sub> = -30 mA	Switch ON, See <a href="#">Figure 10</a>	25°C	4.5 V	0.75	1.3	Ω	
			Full			1.3			
Δr <sub>on</sub>	ON-state resistance match between channels	V <sub>NO</sub> or V <sub>NC</sub> = 2.5 V, I <sub>COM</sub> = -30 mA	Switch ON, See <a href="#">Figure 10</a>	25°C	4.5 V	0.1		Ω	
r <sub>on(flat)</sub>	ON-state resistance flatness	0 ≤ V <sub>NO</sub> or V <sub>NC</sub> ≤ V <sub>+</sub> , I <sub>COM</sub> = -30 mA	Switch ON, See <a href="#">Figure 10</a>	25°C	4.5 V	0.233		Ω	
		V <sub>NO</sub> or V <sub>NC</sub> = 1 V, 1.5 V, 2.5 V, I <sub>COM</sub> = -30 mA		25°C		0.15			
I <sub>NC(OFF)</sub> , I <sub>NO(OFF)</sub>	NC, NO OFF leakage current	V <sub>NC</sub> or V <sub>NO</sub> = 4.5 V, V <sub>COM</sub> = 0	Switch OFF, See <a href="#">Figure 12</a>	25°C	5.5 V	-6	0.2	6	nA
			Full			-150	150		
I <sub>NC(ON)</sub> , I <sub>NO(ON)</sub>	NC, NO ON leakage current	V <sub>NC</sub> or V <sub>NO</sub> = 4.5 V, V <sub>COM</sub> = Open	Switch ON, See <a href="#">Figure 13</a>	25°C	5.5 V	-6	2.8	6	nA
			Full			-150	150		
I <sub>COM(ON)</sub>	COM ON leakage current	V <sub>NC</sub> or V <sub>NO</sub> = 4.5 V or Open, V <sub>COM</sub> = 4.5 V	Switch ON, See <a href="#">Figure 13</a>	25°C	5.5 V	-8	0.47	8	nA
			Full			-150	150		
<b>DIGITAL INPUTS (IN)</b>									
V <sub>IH</sub>	Input logic high			Full		2.4	5.5	V	
V <sub>IL</sub>	Input logic low			Full		0	0.8	V	
I <sub>IH</sub> , I <sub>IL</sub>	Input leakage current	V <sub>IN</sub> = 5.5 V or 0		Full	5.5 V	-1	1	μA	

(1) T<sub>A</sub> = 25°C

## Electrical Characteristics for 5-V Supply (continued)

 $V_+ = 4.5 \text{ V to } 5.5 \text{ V}$  and  $T_A = -40^\circ\text{C to } +125^\circ\text{C}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS		$T_A$	$V_+$	MIN	TYP <sup>(1)</sup>	MAX	UNIT
<b>DYNAMIC</b>									
$t_{ON}$	Turn-on time	$V_{COM} = V_+$ , $R_L = 50 \Omega$ ,	$C_L = 35 \text{ pF}$ , See <a href="#">Figure 15</a>	25°C	4.5 V to 5.5 V		20	35	ns
				Full					
$t_{OFF}$	Turn-off time	$V_{COM} = V_+$ , $R_L = 50 \Omega$ ,	$C_L = 35 \text{ pF}$ , See <a href="#">Figure 15</a>	25°C	4.5 V to 5.5 V		15	20	ns
				Full					
$t_{BBM}$	Break-before-make time	$V_{NC} = V_{NO} = V_+ / 2$ , $R_L = 50 \Omega$ ,	$C_L = 35 \text{ pF}$ , See <a href="#">Figure 16</a>	25°C	4.5 V to 5.5 V		1	12	14.5
				Full					
$Q_C$	Charge injection	$C_L = 1 \text{ nF}$ , $V_{GEN} = 0 \text{ V}$ ,	See <a href="#">Figure 19</a>	25°C	5 V		36		pC
$C_{NC(OFF)}$ , $C_{NO(OFF)}$	NC, NO OFF capacitance	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch OFF,	See <a href="#">Figure 13</a>	25°C	5 V		23		pF
$C_{NC(ON)}$ , $C_{NO(ON)}$	NC, NO ON capacitance	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch ON,	See <a href="#">Figure 13</a>	25°C	5 V		84		pF
$C_{COM(ON)}$	COM ON capacitance	$V_{COM} = V_+$ or GND, Switch ON,	See <a href="#">Figure 13</a>	25°C	5 V		84		pF
$C_{IN}$	Digital input capacitance	$V_{IN} = V_+$ or GND,	See <a href="#">Figure 13</a>	25°C	5 V		2.1		pF
BW	Bandwidth	$R_L = 50 \Omega$ , Switch ON,	See <a href="#">Figure 16</a>	25°C	5 V		100		MHz
$O_{ISO}$	OFF isolation	$R_L = 50 \Omega$ , $f = 1 \text{ MHz}$ ,	Switch OFF, See <a href="#">Figure 17</a>	25°C	5 V		-65		dB
$X_{TALK}$	Crosstalk	$R_L = 50 \Omega$ , $f = 1 \text{ MHz}$ ,	Switch ON, See <a href="#">Figure 18</a>	25°C	5 V		-65		dB
THD	Total harmonic distortion	$R_L = 600 \Omega$ , $C_L = 50 \text{ pF}$ ,	$f = 600 \text{ Hz to } 20 \text{ kHz}$ , See <a href="#">Figure 19</a>	25°C	5 V		0.01%		
<b>SUPPLY</b>									
$I_+$	Positive supply current	$V_{IN} = V_+$ or GND,	Switch ON or OFF	25°C	5.5 V			0.1	$\mu\text{A}$
				Full					

## 6.6 Electrical Characteristics for 3.3-V Supply

 $V_+ = 3 \text{ V to } 3.6 \text{ V}$  and  $T_A = -40^\circ\text{C to } +125^\circ\text{C}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS		$T_A$	$V_+$	MIN	TYP <sup>(1)</sup>	MAX	UNIT
<b>ANALOG SWITCH</b>									
$V_{COM}$ , $V_{NO}$ , $V_{NC}$	Analog signal range					0		$V_+$	V
$r_{peak}$	Peak ON-state resistance	$0 \leq V_{NO}$ or $V_{NC} \leq V_+$ , $I_{COM} = -24 \text{ mA}$ ,	Switch ON, See <a href="#">Figure 10</a>	25°C	3 V		1.35	2.2	$\Omega$
				Full					
$r_{on}$	ON-state resistance	$V_{NO}$ or $V_{NC} = 2 \text{ V}$ , $I_{COM} = -24 \text{ mA}$ ,	Switch ON, See <a href="#">Figure 10</a>	25°C	3 V		1.15	1.8	$\Omega$
				Full					
$\Delta r_{on}$	ON-state resistance match between channels	$V_{NO}$ or $V_{NC} = 2 \text{ V}$ , $0.8 \text{ V}$ , $I_{COM} = -24 \text{ mA}$ ,	Switch ON, See <a href="#">Figure 10</a>	25°C	3 V		0.11		$\Omega$
$r_{on(Flat)}$	ON-state resistance flatness	$0 \leq V_{NO}$ or $V_{NC} \leq V_+$ , $I_{COM} = -24 \text{ mA}$ , $V_{NO}$ or $V_{NC} = 2 \text{ V}$ , $0.8 \text{ V}$ , $I_{COM} = -24 \text{ mA}$ ,	Switch ON, See <a href="#">Figure 10</a>	25°C	3 V		0.225		$\Omega$
				25°C					
$I_{NC(OFF)}$ , $I_{NO(OFF)}$	NC, NO OFF leakage current	$V_{NC}$ or $V_{NO} = 3 \text{ V}$ , $V_{COM} = 0$ ,	Switch OFF, See <a href="#">Figure 11</a>	25°C	3.6 V		0.2		nA
$I_{NC(ON)}$ , $I_{NO(ON)}$	NC, NO ON leakage current	$V_{NC}$ or $V_{NO} = 3 \text{ V}$ , $V_{COM} = \text{Open}$ ,	Switch ON, See <a href="#">Figure 12</a>	25°C	3.6 V		2.8		nA
$I_{COM(ON)}$	COM ON leakage current	$V_{NC}$ or $V_{NO} = 3 \text{ V}$ or Open, $V_{COM} = 3 \text{ V}$ ,	Switch ON, See <a href="#">Figure 12</a>	25°C	3.6 V		0.47		nA

 (1)  $T_A = 25^\circ\text{C}$

**Electrical Characteristics for 3.3-V Supply (continued)**
 $V_+ = 3\text{ V to }3.6\text{ V}$  and  $T_A = -40^\circ\text{C to }+125^\circ\text{C}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS		$T_A$	$V_+$	MIN	TYP <sup>(1)</sup>	MAX	UNIT
<b>DIGITAL INPUTS (IN)</b>									
$V_{IH}$	Input logic high			Full		2		5.5	V
$V_{IL}$	Input logic low			Full		0		0.6	V
$I_{IH}, I_{IL}$	Input leakage current	$V_{IN} = 5.5\text{ V or }0$		Full	3.6 V	-1		1	$\mu\text{A}$
<b>DYNAMIC</b>									
$t_{ON}$	Turn-on time	$V_{COM} = V_+,$ $R_L = 50\ \Omega$	$C_L = 35\text{ pF},$ See <a href="#">Figure 15</a>	25°C	3 V to 3.6 V		30	40	ns
				Full					
$t_{OFF}$	Turn-off time	$V_{COM} = V_+,$ $R_L = 50\ \Omega$	$C_L = 35\text{ pF},$ See <a href="#">Figure 15</a>	25°C	3 V to 3.6 V		20	25	ns
				Full					
$t_{BBM}$	Break-before-make time	$V_{NC} = V_{NO} = V_+ / 2,$ $R_L = 50\ \Omega$	$C_L = 35\text{ pF},$ See <a href="#">Figure 16</a>	25°C	3 V to 3.6 V		1	21	29
				Full					
$Q_C$	Charge injection	$C_L = 1\text{ nF}, V_{GEN} = 0\text{ V}$		25°C	3.3 V		20		pC
$C_{NC(OFF)},$ $C_{NO(OFF)}$	NC, NO OFF capacitance	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch OFF		25°C	3.3 V		23		pF
$C_{NC(ON)},$ $C_{NO(ON)}$	NC, NO ON capacitance	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch ON		25°C	3.3 V		84		pF
$C_{COM(ON)}$	COM ON capacitance	$V_{COM} = V_+$ or GND, Switch ON		25°C	3.3 V		84		pF
$C_{IN}$	Digital input capacitance	$V_{IN} = V_+$ or GND		25°C	3.3 V		2.1		pF
BW	Bandwidth	$R_L = 50\ \Omega,$ Switch ON		25°C	3.3 V		100		MHz
$O_{ISO}$	OFF isolation	$R_L = 50\ \Omega,$ $f = 1\text{ MHz}$		25°C	3.3 V		-65		dB
$X_{TALK}$	Crosstalk	$R_L = 50\ \Omega,$ $f = 1\text{ MHz}$		25°C	3.3 V		-65		dB
THD	Total harmonic distortion	$R_L = 600\ \Omega,$ $C_L = 50\text{ pF}$		25°C	3.3 V		0.015%		
<b>SUPPLY</b>									
$I_+$	Positive supply current	$V_{IN} = V_+$ or GND	Switch ON or OFF	25°C	3.6 V			0.1	$\mu\text{A}$
				Full					

## 6.7 Electrical Characteristics For 2.5-V Supply

 $V_+ = 2.3 \text{ V to } 2.7 \text{ V}$  and  $T_A = -40^\circ\text{C to } +125^\circ\text{C}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS		$T_A$	$V_+$	MIN	TYP <sup>(1)</sup>	MAX	UNIT
<b>ANALOG SWITCH</b>									
$V_{COM}, V_{NO}, V_{NC}$	Analog signal range					0		$V_+$	V
$r_{peak}$	Peak ON-state resistance	$0 \leq V_{NO}$ or $V_{NC} \leq V_+$ , $I_{COM} = -8 \text{ mA}$	Switch ON, See <a href="#">Figure 10</a>	25°C Full	2.5 V		1.7 2.9	2.9	$\Omega$
$r_{on}$	ON-state resistance	$V_{NO}$ or $V_{NC} = 1.8 \text{ V}$ , $I_{COM} = -8 \text{ mA}$	Switch ON, See <a href="#">Figure 10</a>	25°C Full	2.5 V		1.45 2.3	2.3	$\Omega$
$\Delta r_{on}$	ON-state resistance match between channels	$V_{NO}$ or $V_{NC} = 0.8 \text{ V}, 1.8 \text{ V}$ , $I_{COM} = -8 \text{ mA}$	Switch ON, See <a href="#">Figure 10</a>	25°C	2.5 V		0.7		$\Omega$
$r_{on(Flat)}$	ON-state resistance flatness	$0 \leq V_{NO}$ or $V_{NC} \leq V_+$ , $I_{COM} = -8 \text{ mA}$ $V_{NO}$ or $V_{NC} = 0.8 \text{ V}, 1.8 \text{ V}$ , $I_{COM} = -8 \text{ mA}$	Switch ON, See <a href="#">Figure 10</a>	25°C 25°C	2.5 V		0.5 0.45		$\Omega$
$I_{NC(OFF)}, I_{NO(OFF)}$	NC, NO Off leakage current	$V_{NC}$ or $V_{NO} = 2.3 \text{ V}$ , $V_{COM} = 0$	Switch OFF, See <a href="#">Figure 11</a>	25°C	2.7 V		0.2		nA
$I_{NC(ON)}, I_{NO(ON)}$	NC, NO On leakage current	$V_{NC}$ or $V_{NO} = 2.3 \text{ V}$ , $V_{COM} = \text{Open}$	Switch ON, See <a href="#">Figure 12</a>	25°C	2.7 V		2.8		nA
$I_{COM(ON)}$	COM On leakage current	$V_{NC}$ or $V_{NO} = 2.3 \text{ V}$ or Open, $V_{COM} = 2.3 \text{ V}$	Switch ON, See <a href="#">Figure 12</a>	25°C	2.7 V		0.47		nA
<b>DIGITAL INPUTS (IN)</b>									
$V_{IH}$	Input logic high			Full		1.8		5.5	V
$V_{IL}$	Input logic low			Full		0	0.6		V
$I_{IH}, I_{IL}$	Input leakage current	$V_{IN} = 5.5 \text{ V}$ or 0		Full	2.7 V	-1		1	$\mu\text{A}$
<b>DYNAMIC</b>									
$t_{ON}$	Turn-on time	$V_{COM} = V_+$ , $R_L = 50 \Omega$ ,	$C_L = 35 \text{ pF}$ , See <a href="#">Figure 15</a>	25°C Full	2.3 V to 2.7 V		40 55	55 70	ns
$t_{OFF}$	Turn-off time	$V_{COM} = V_+$ , $R_L = 50 \Omega$ ,	$C_L = 35 \text{ pF}$ , See <a href="#">Figure 15</a>	25°C Full	2.3 V to 2.7 V		30 55	40 55	ns
$t_{BBM}$	Break-before-make time	$V_{NC} = V_{NO} = V_+ / 2$ , $R_L = 50 \Omega$ ,	$C_L = 35 \text{ pF}$ , See <a href="#">Figure 16</a>	25°C Full	2.3 V to 2.7 V	1	33	39	ns
$Q_C$	Charge injection	$C_L = 1 \text{ nF}$ , $V_{GEN} = 0 \text{ V}$ ,	See <a href="#">Figure 19</a>	25°C	2.5 V		13		pC
$C_{NC(OFF)}, C_{NO(OFF)}$	NC, NO OFF capacitance	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch OFF,	See <a href="#">Figure 14</a>	25°C	2.5 V		23		pF
$C_{NC(ON)}, C_{NO(ON)}$	NC, NO ON capacitance	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch ON,	See <a href="#">Figure 14</a>	25°C	2.5 V		84		pF
$C_{COM(ON)}$	COM ON capacitance	$V_{COM} = V_+$ or GND, Switch ON,	See <a href="#">Figure 14</a>	25°C	2.5 V		84		pF
$C_{IN}$	Digital input capacitance	$V_{IN} = V_+$ or GND,	See <a href="#">Figure 14</a>	25°C	2.5 V		2.1		pF
BW	Bandwidth	$R_L = 50 \Omega$ , Switch ON,	See <a href="#">Figure 16</a>	25°C	2.5 V		100		MHz
$O_{ISO}$	OFF isolation	$R_L = 50 \Omega$ , $f = 1 \text{ MHz}$ ,	Switch OFF, See <a href="#">Figure 17</a>	25°C	2.5 V		-64		dB
$X_{TALK}$	Crosstalk	$R_L = 50 \Omega$ , $f = 1 \text{ MHz}$ ,	Switch ON, See <a href="#">Figure 18</a>	25°C	2.5 V		-64		dB
THD	Total harmonic distortion	$R_L = 600 \Omega$ , $C_L = 50 \text{ pF}$ ,	$f = 600 \text{ Hz}$ to 20 kHz, See <a href="#">Figure 19</a>	25°C	2.5 V		0.025%		
<b>SUPPLY</b>									
$I_+$	Positive supply current	$V_{IN} = V_+$ or GND,	Switch ON or OFF	25°C Full	2.7 V			0.1 0.5	$\mu\text{A}$

 (1)  $T_A = 25^\circ\text{C}$



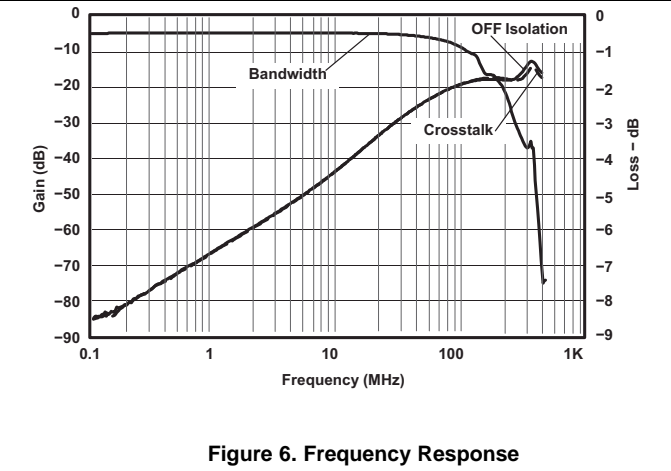
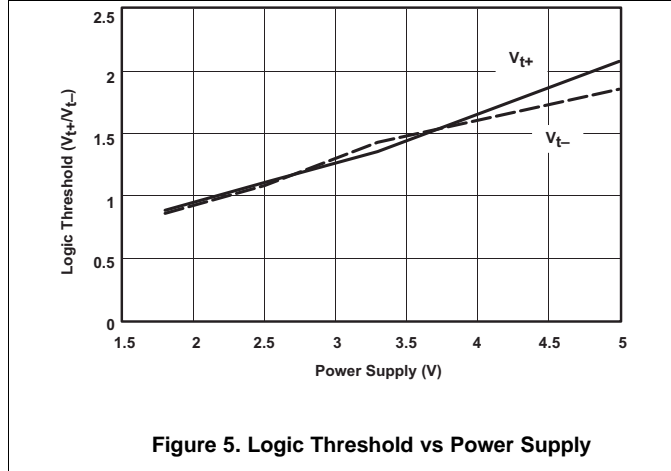
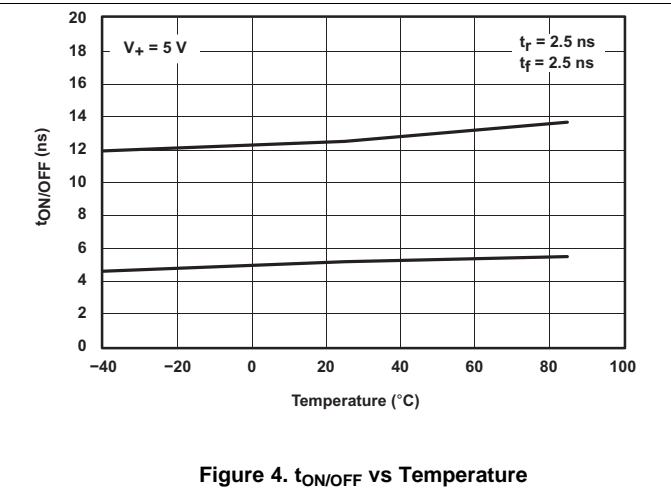
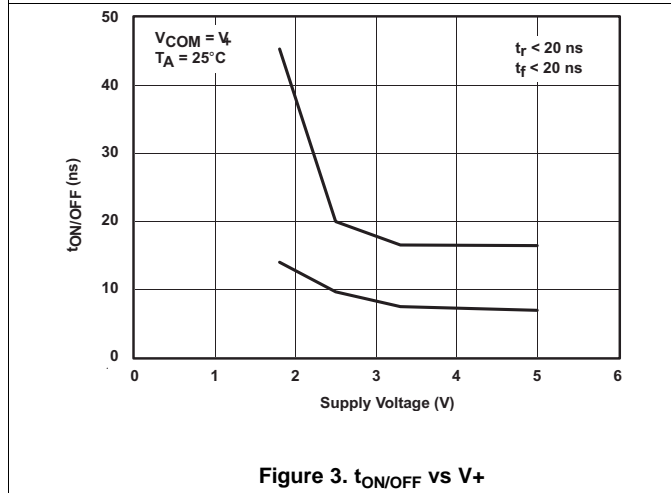
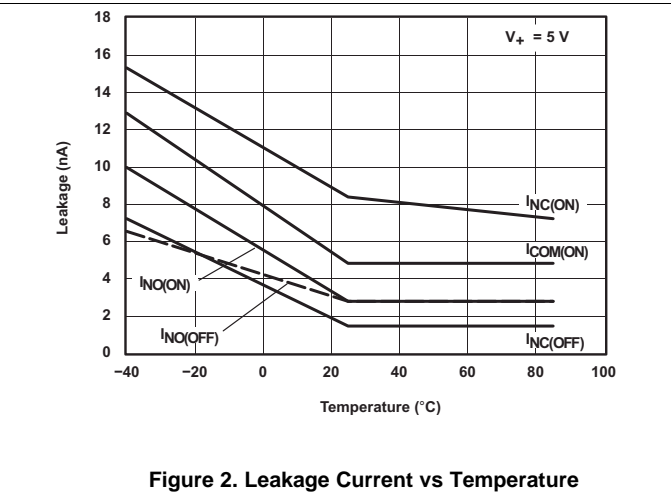
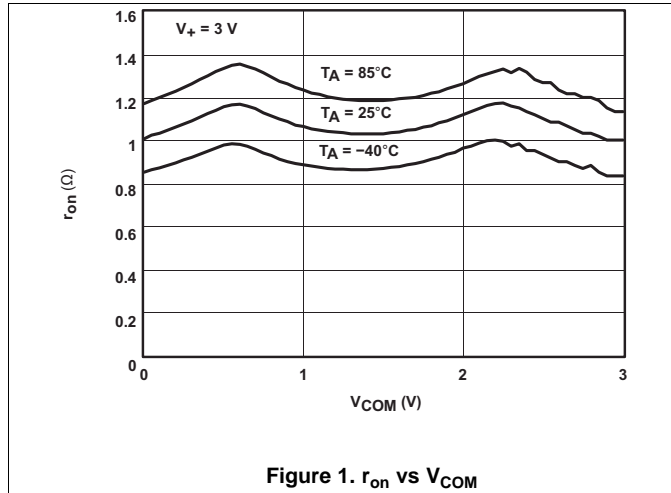
## 6.8 Electrical Characteristics For 1.8-V Supply

 $V_+ = 1.65\text{ V to }1.95\text{ V}$  and  $T_A = -40^\circ\text{C to }+125^\circ\text{C}$  (unless otherwise noted)

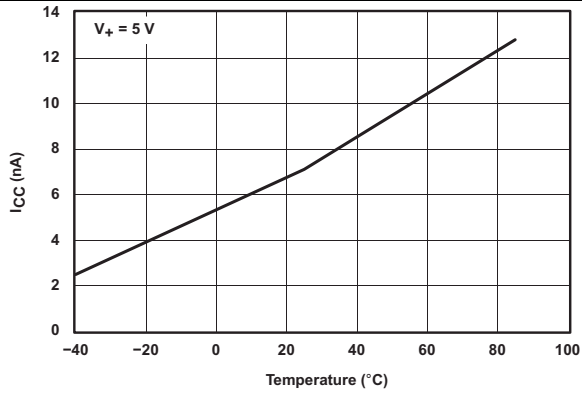
PARAMETER		TEST CONDITIONS		$T_A$	$V_+$	MIN	TYP <sup>(1)</sup>	MAX	UNIT
<b>ANALOG SWITCH</b>									
$V_{COM}, V_{NO}, V_{NC}$	Analog signal range					0		$V_+$	V
$r_{peak}$	Peak ON-state resistance	$0 \leq V_{NO}$ or $V_{NC} \leq V_+$ , $I_{COM} = -2\text{ mA}$	Switch ON, See <a href="#">Figure 10</a>	25°C Full	1.8 V		4	5.2 5.2	$\Omega$
$r_{on}$	ON-state resistance	$V_{NO}$ or $V_{NC} = 1.5\text{ V}$ , $I_{COM} = -2\text{ mA}$	Switch ON, See <a href="#">Figure 10</a>	25°C Full	1.8 V		1.7	3.5 3.5	$\Omega$
$\Delta r_{on}$	ON-state resistance match between channels	$V_{NO}$ or $V_{NC} = 0.6\text{ V}, 1.5\text{ V}$ , $I_{COM} = -2\text{ mA}$	Switch ON, See <a href="#">Figure 10</a>	25°C Full	1.8 V		0.7	0.7	$\Omega$
$r_{on(Flat)}$	ON-state resistance flatness	$0 \leq V_{NO}$ or $V_{NC} \leq V_+$ , $I_{COM} = -2\text{ mA}$ $V_{NO}$ or $V_{NC} = 0.6\text{ V}, 1.5\text{ V}$ , $I_{COM} = -2\text{ mA}$	Switch ON, See <a href="#">Figure 11</a>	25°C Full 25°C Full	1.8 V		1.85 1.85 0.9 0.9		$\Omega$
$I_{NC(OFF)}, I_{NO(OFF)}$	NC, NO Off leakage current	$V_{NC}$ or $V_{NO} = 1.65\text{ V}$ , $V_{COM} = 0$	Switch OFF, See <a href="#">Figure 11</a>	25°C	1.95 V		0.2		nA
$I_{NC(ON)}, I_{NO(ON)}$	NC, NO On leakage current	$V_{NC}$ or $V_{NO} = 1.65\text{ V}$ , $V_{COM} = \text{Open}$	Switch ON, See <a href="#">Figure 12</a>	25°C	1.95 V		2.8		nA
$I_{COM(ON)}$	COM On leakage current	$V_{NC}$ or $V_{NO} = 1.65\text{ V}$ or Open, $V_{COM} = 1.65\text{ V}$	Switch ON, See <a href="#">Figure 12</a>	25°C	1.95 V		0.47		nA
<b>DIGITAL INPUTS (IN)</b>									
$V_{IH}$	Input logic high			Full		1.5		5.5	V
$V_{IL}$	Input logic low			Full		0		0.6	V
$I_{IH}, I_{IL}$	Input leakage current	$V_{IN} = 5.5\text{ V}$ or 0		Full	1.95 V	-1		1	$\mu\text{A}$
<b>DYNAMIC</b>									
$t_{ON}$	Turn-on time	$V_{COM} = V_+$ , $R_L = 50\ \Omega$ ,	$C_L = 35\text{ pF}$ , See <a href="#">Figure 15</a>	25°C Full	1.65 V to 1.95 V		65	70 95	ns
$t_{OFF}$	Turn-off time	$V_{COM} = V_+$ , $R_L = 50\ \Omega$ ,	$C_L = 35\text{ pF}$ , See <a href="#">Figure 15</a>	25°C Full	1.65 V to 1.95 V		40	55 70	ns
$t_{BBM}$	Break-before-make time	$V_{NC} = V_{NO} = V_+ / 2$ , $R_L = 50\ \Omega$ ,	$C_L = 35\text{ pF}$ , See <a href="#">Figure 15</a>	25°C Full	1.65 V to 1.95 V		1 0.5	60 72	ns
$Q_C$	Charge injection	$C_L = 1\text{ nF}$ , $V_{GEN} = 0\text{ V}$ ,	See <a href="#">Figure 19</a>	25°C	1.8 V		13		pC
$C_{NC(OFF)}, C_{NO(OFF)}$	NC, NO OFF capacitance	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch OFF,	See <a href="#">Figure 14</a>	25°C	1.8 V		23		pF
$C_{NC(ON)}, C_{NO(ON)}$	NC, NO ON capacitance	$V_{NC}$ or $V_{NO} = V_+$ or GND, Switch ON,	See <a href="#">Figure 14</a>	25°C	1.8 V		84		pF
$C_{COM(ON)}$	COM ON capacitance	$V_{COM} = V_+$ or GND, Switch ON,	See <a href="#">Figure 14</a>	25°C	1.8 V		84		pF
$C_{IN}$	Digital input capacitance	$V_{IN} = V_+$ or GND,	See <a href="#">Figure 14</a>	25°C	1.8 V		2.1		pF
BW	Bandwidth	$R_L = 50\ \Omega$ , Switch ON,	See <a href="#">Figure 16</a>	25°C	1.8 V		100		MHz
$O_{ISO}$	OFF isolation	$R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ ,	Switch OFF, See <a href="#">Figure 17</a>	25°C	1.8 V		-63		dB
$X_{TALK}$	Crosstalk	$R_L = 50\ \Omega$ , $f = 1\text{ MHz}$ ,	Switch ON, See <a href="#">Figure 18</a>	25°C	1.8 V		-63		dB
<b>SUPPLY</b>									
$I_+$	Positive supply current	$V_{IN} = V_+$ or GND,	Switch ON or OFF	25°C Full	1.95 V			0.1 0.5	$\mu\text{A}$

(1)  $T_A = 25^\circ\text{C}$

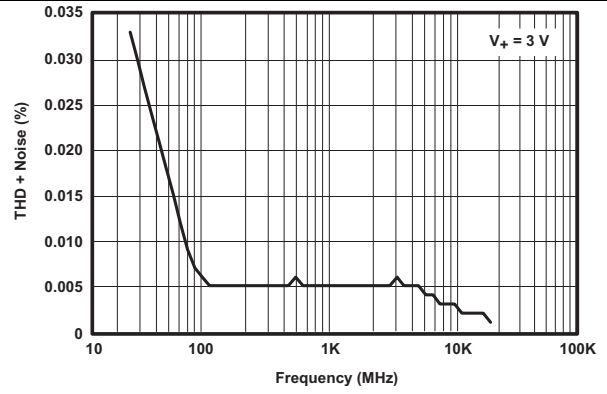
### 6.9 Typical Characteristics



**Typical Characteristics (continued)**



**Figure 7. Power-Supply Current vs Temperature**



**Figure 8. Total Harmonic Distortion (THD) vs Frequency**

## 7 Parameter Measurement Information

**Table 1. Parameter Description**

SYMBOL	DESCRIPTION
$V_{COM}$	Voltage at COM
$V_{NC}$	Voltage at NC
$V_{NO}$	Voltage at NO
$r_{on}$	Resistance between COM and NC or COM and NO ports, when the channel is ON
$r_{peak}$	Peak ON-state resistance over a specified voltage range
$\Delta r_{on}$	Difference of $r_{on}$ between channels
ron(flat)	Difference between the maximum and minimum value of $r_{on}$ in a channel over the specified range of conditions
$I_{NC(OFF)}$	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state under worst-case input and output conditions
$I_{NO(OFF)}$	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state under worst-case input and output conditions
$I_{NC(ON)}$	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state and the output (COM) being open
$I_{NO(ON)}$	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) being open
$I_{COM(ON)}$	Leakage current measured at the COM port, with the corresponding channel (COM to NO or COM to NC) in the ON state and the output (NC or NO) being open
$V_{IH}$	Minimum input voltage for logic high for the control input (IN)
$V_{IL}$	Minimum input voltage for logic low for the control input (IN)
$V_{IN}$	Voltage at IN
$I_{IH}, I_{IL}$	Leakage current measured at IN
$t_{ON}$	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog outputs (COM, NC, or NO) signal, when the switch is turning ON.
$t_{OFF}$	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog outputs (COM, NC, or NO) signal, when the switch is turning OFF.
$t_{BBM}$	Break-before-make time. This parameter is measured under the specified range of conditions and by the propagation delay between the output of two adjacent analog channels (NC and NO), when the control signal changes state.
$Q_C$	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NC, NO, or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_O$ , $C_L$ is the load capacitance, and $\Delta V_O$ is the change in analog output voltage.
$C_{NC(OFF)}$	Capacitance at the NC port when the corresponding channel (NC to COM) is OFF
$C_{NO(OFF)}$	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
$C_{NC(ON)}$	Capacitance at the NC port when the corresponding channel (NC to COM) is ON
$C_{NO(ON)}$	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
$C_{COM(ON)}$	Capacitance at the COM port when the corresponding channel (COM to NC or COM to NO) is ON
$C_{IN}$	Capacitance of IN
$O_{ISO}$	OFF isolation of the switch is a measurement OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NC to COM or NO to COM) in the OFF state.
$X_{TALK}$	Crosstalk is a measurement of unwanted signal coupling from an ON channel to an OFF channel (NC to NO or NO to NC). This is measured in a specific frequency and in dB.
BW	Bandwidth of the switch. This is the frequency in which the gain of an ON channel is -3 dB below the DC gain.
$I_+$	Static power-supply current with the control (IN) pin at $V_+$ or GND
$\Delta I_+$	This is the increase in $I_+$ for each control (IN) input that is at the specified voltage, rather than at $V_+$ or GND.

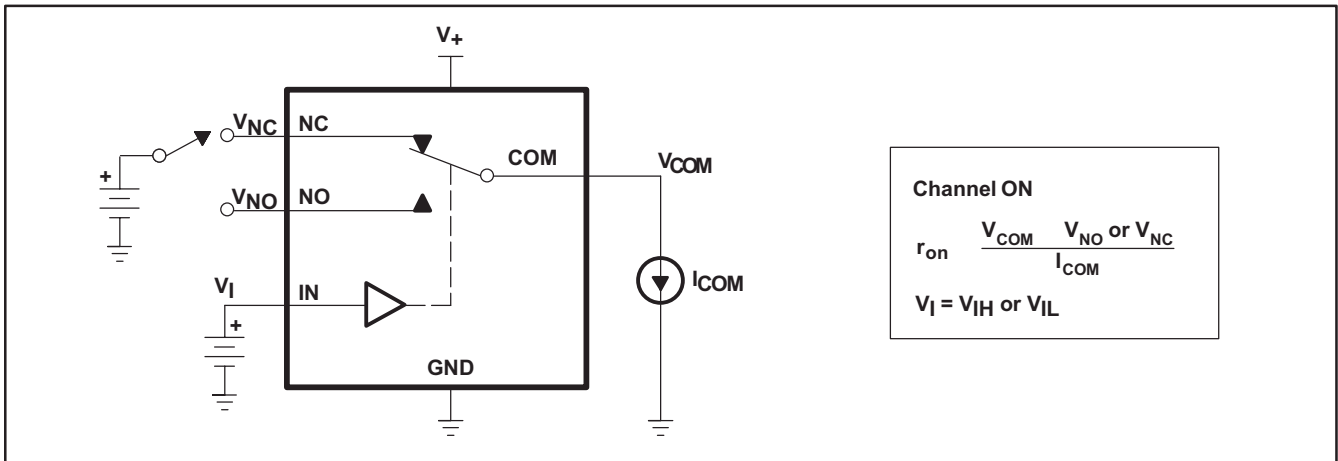


Figure 9. On-State Resistance ( $r_{on}$ )

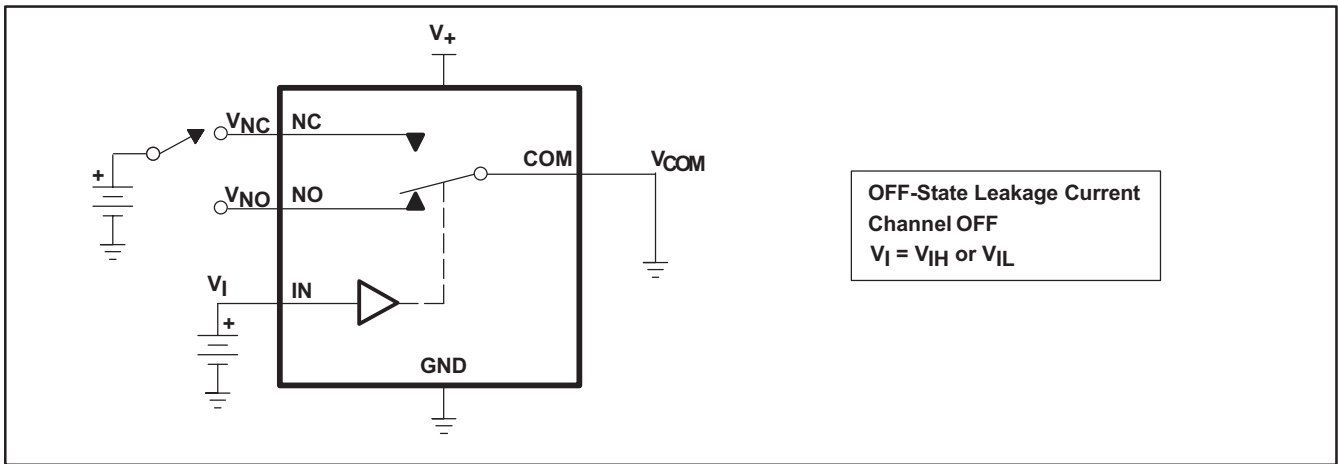


Figure 10. Off-State Leakage Current ( $I_{NC(OFF)}$ ,  $I_{NO(OFF)}$ )

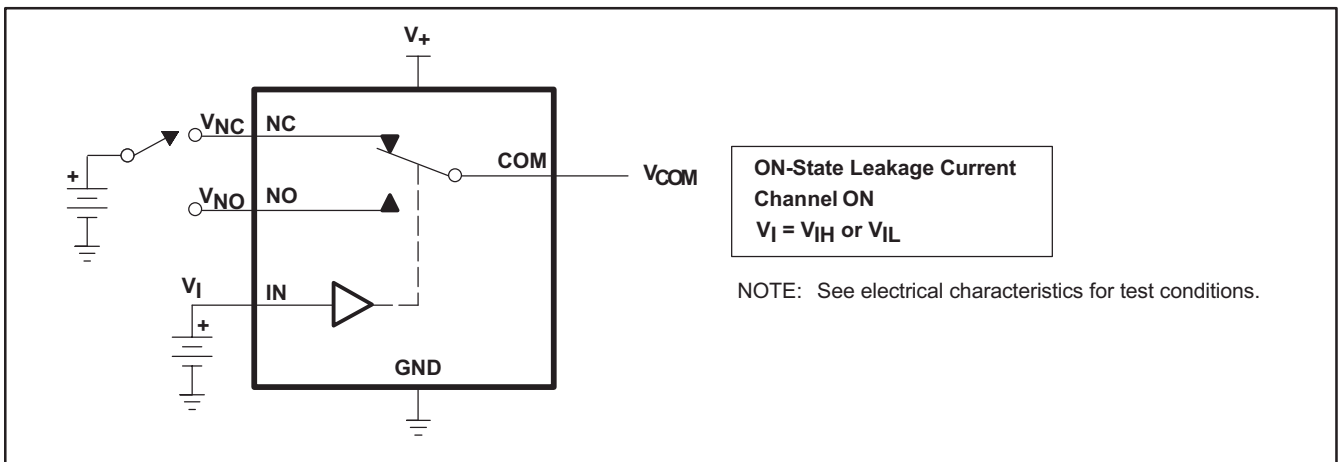


Figure 11. On-State Leakage Current ( $I_{COM(ON)}$ ,  $I_{NC(ON)}$ ,  $I_{NO(ON)}$ )

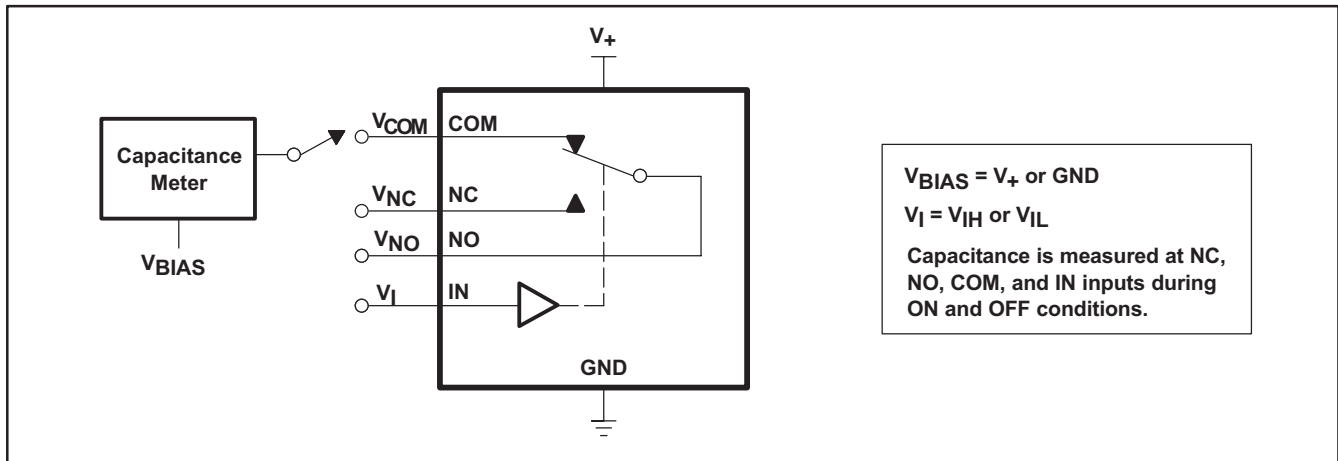
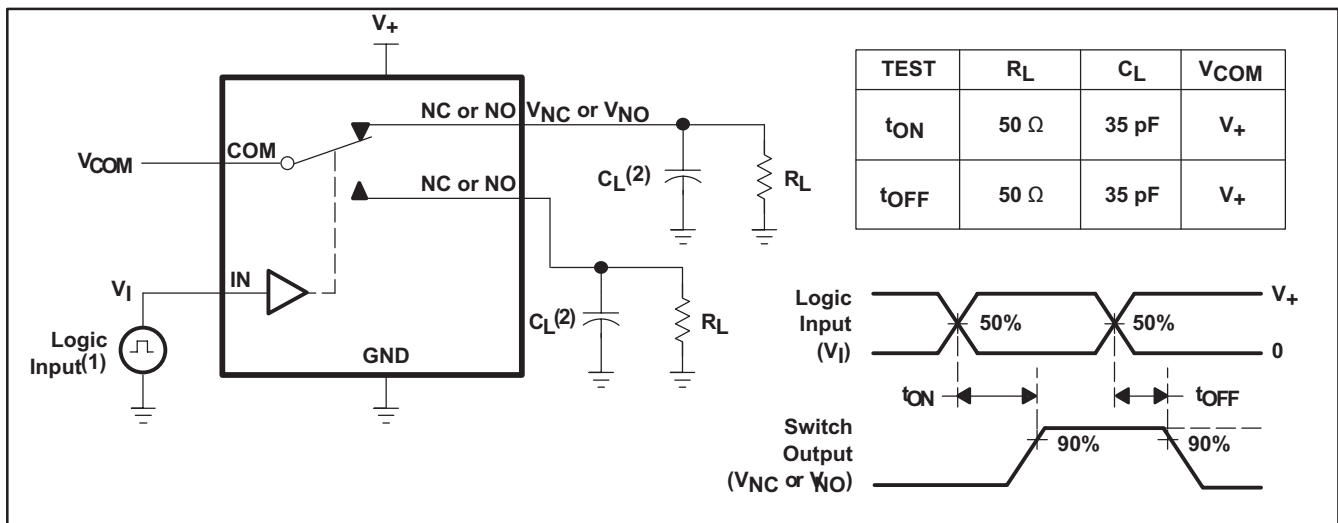
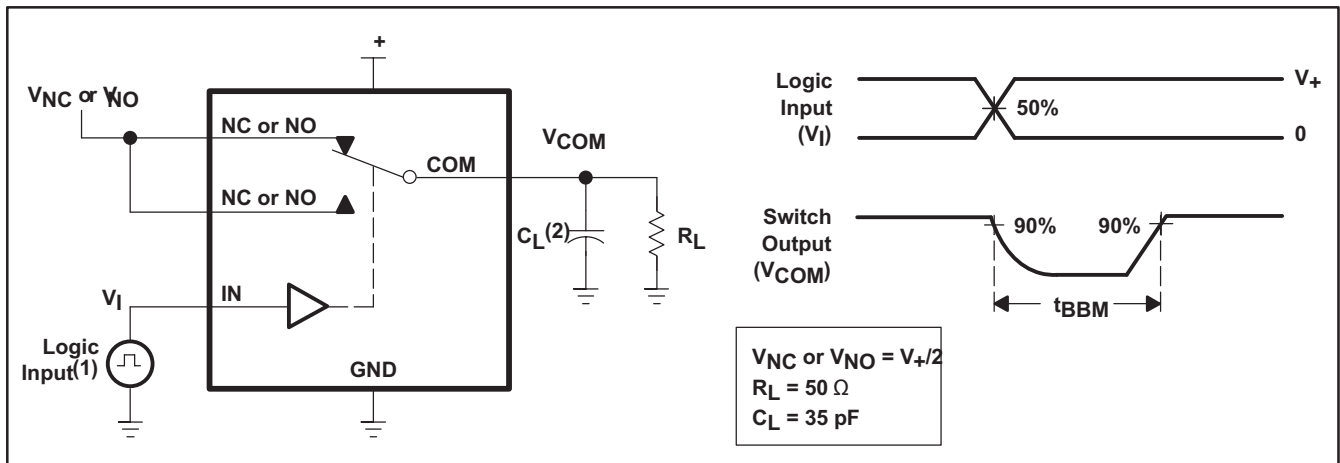


Figure 12. Capacitance ( $C_I$ ,  $C_{COM(ON)}$ ,  $C_{NC(OFF)}$ ,  $C_{NO(OFF)}$ ,  $C_{NC(ON)}$ ,  $C_{NO(ON)}$ )



(1) All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> < 5 ns, t<sub>f</sub> < 5 ns.  
 (2) C<sub>L</sub> includes probe and jig capacitance.

Figure 13. Turn-On (t<sub>ON</sub>) and Turn-Off Time (t<sub>OFF</sub>)



(1) All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> < 5 ns, t<sub>f</sub> < 5 ns.  
 (2) C<sub>L</sub> includes probe and jig capacitance.

Figure 14. Break-Before-Make Time (t<sub>BBM</sub>)

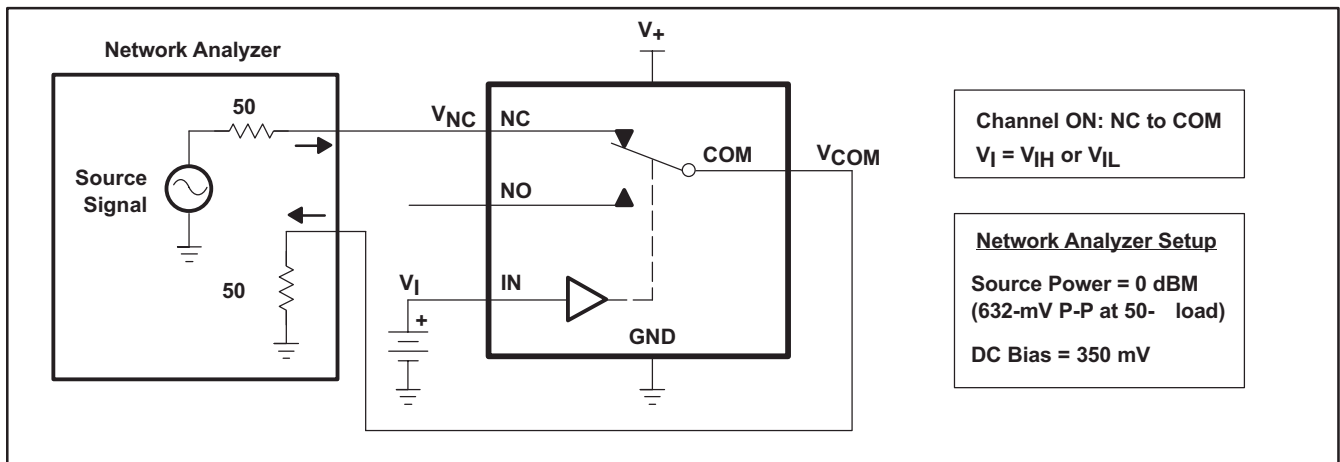


Figure 15. Bandwidth (BW)

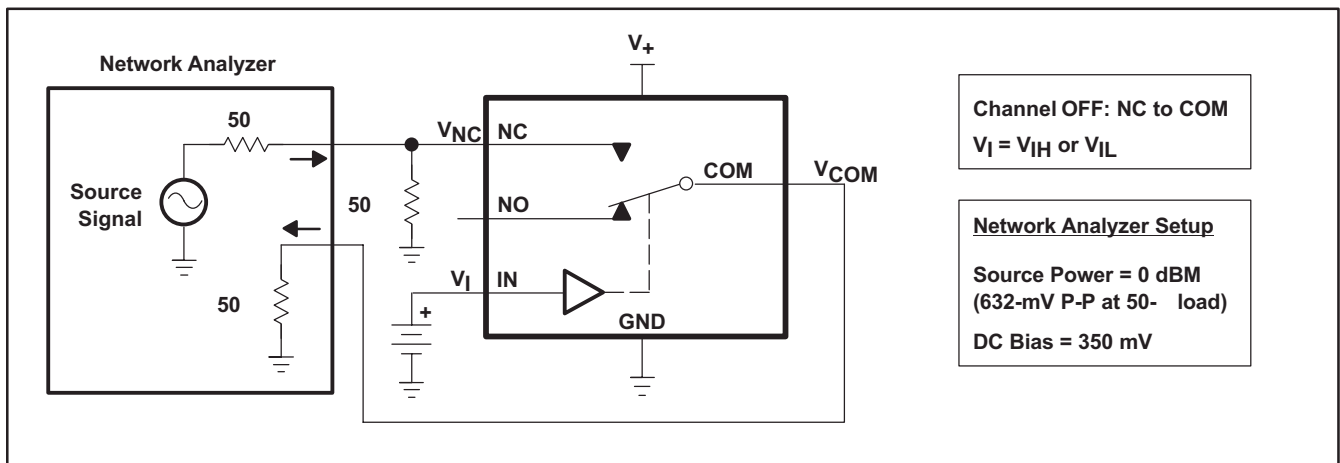


Figure 16. OFF Isolation (O<sub>ISO</sub>)

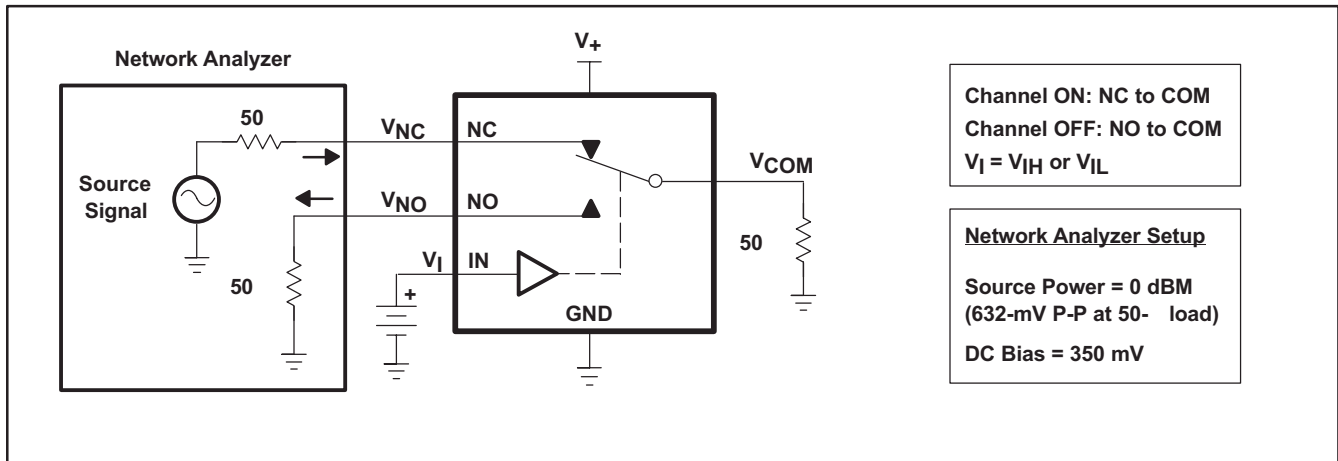
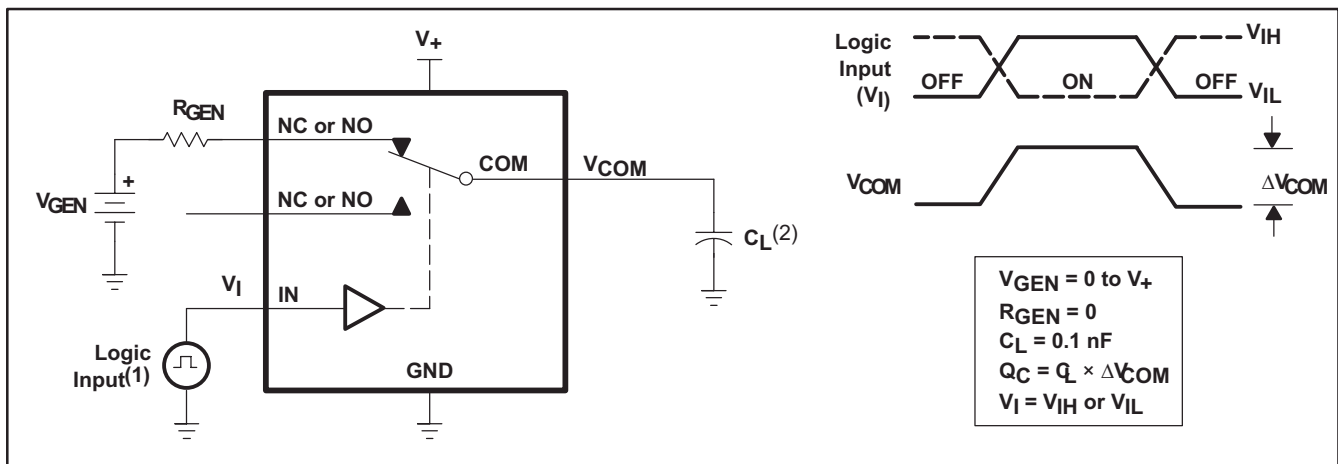
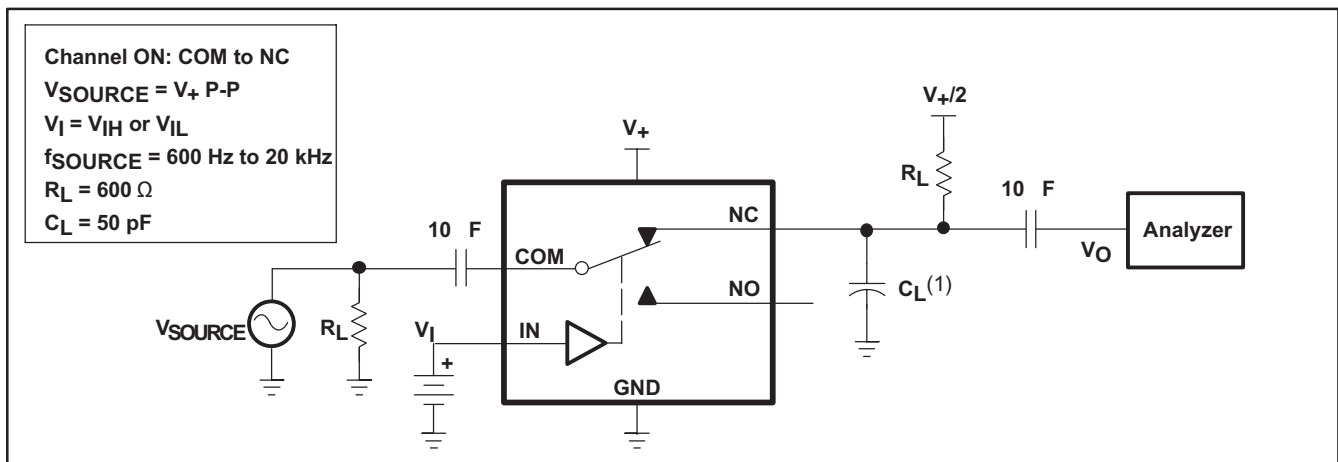


Figure 17. Crosstalk ( $X_{TALK}$ )



- (1) All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5$  ns,  $t_f < 5$  ns.
- (2)  $C_L$  includes probe and jig capacitance.

Figure 18. Charge Injection ( $Q_C$ )



- (1)  $C_L$  includes probe and jig capacitance.

Figure 19. Total Harmonic Distortion (THD)

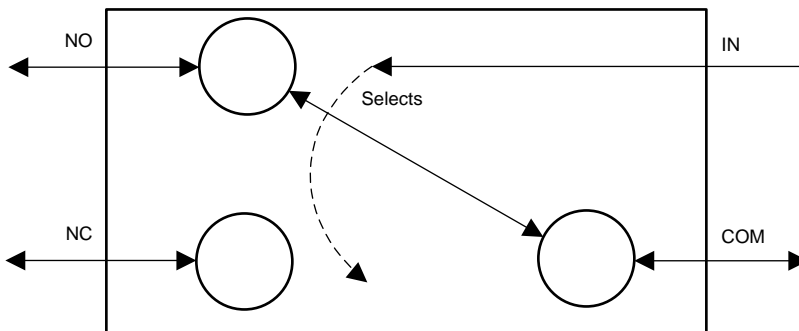


## 8 Detailed Description

### 8.1 Overview

The TS5A3159-Q1 is a single-pole double-throw (SPDT) analog switch designed to operate from 1.65 V to 5.5 V. Either the NO or the NC pin is shorted to the COM pin, depending on the logic level input to the IN pin.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

The main feature of this device is the excellent total harmonic distortion performance and low power consumption. Additionally, the NO, NC, and COM pins can be used as either inputs or outputs.

Table 2. Summary Of Characteristics<sup>(1)</sup>

CONFIGURATION	2:1 MULTIPLEXER / DEMULTIPLEXER (1 × SPDT)
Number of channels	1
ON-state resistance ( $r_{on}$ )	1.3 $\Omega$
ON-state resistance match ( $\Delta r_{on}$ )	0.1 $\Omega$
ON-state resistance flatness ( $r_{on(Flat)}$ )	0.15 $\Omega$
Turn on/turn off time ( $t_{ON} / t_{OFF}$ )	20 ns / 15 ns
Break-before-make time ( $t_{BBM}$ )	12 ns
Charge injection ( $Q_C$ )	36 pC
Bandwidth (BW)	100 MHz
OFF isolation ( $O_{ISO}$ )	-65 dB at 1 MHz
Crosstalk ( $X_{TALK}$ )	-65 dB at 1 MHz
Total harmonic distortion (THD)	0.01%
Leakage current ( $I_{NO(OFF)} / I_{NC(OFF)}$ )	$\pm 6$ nA
Package option	6-pin DBV

(1)  $V_+ = 5$  V and  $T_A = 25^\circ\text{C}$

### 8.4 Device Functional Modes

Table 3 lists the functions for the TS5A3159-Q1 device.

Table 3. Function Table

IN	NC TO COM, COM TO NC	NO TO COM, COM TO NO
L	ON	OFF
H	OFF	ON

## 9 Applications and Implementation

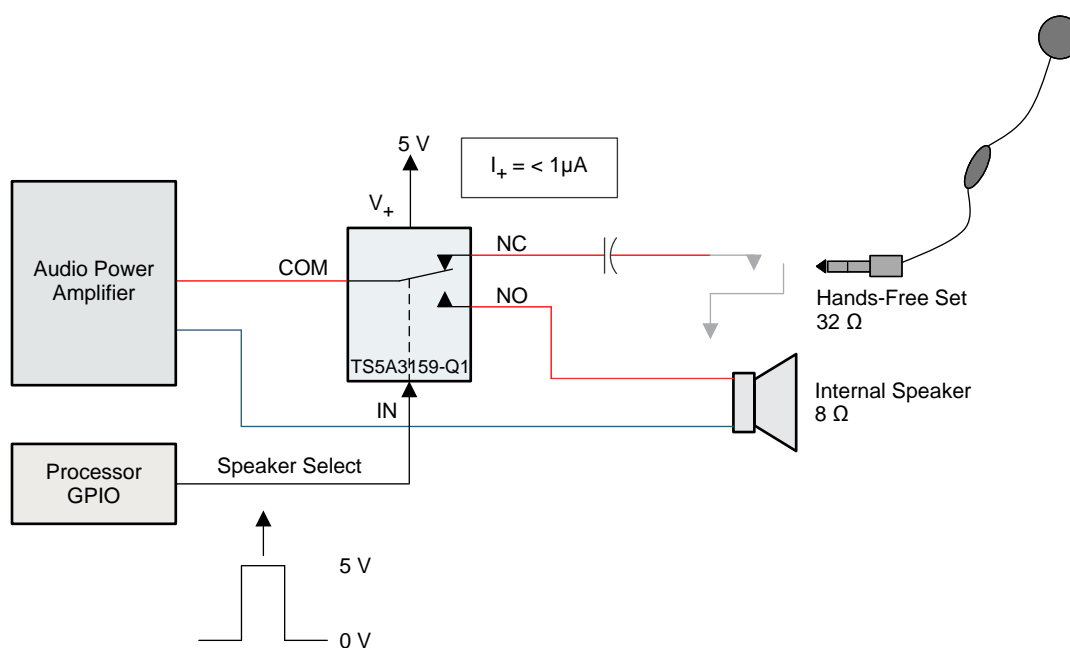
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

Analog switches are commonly used in battery powered applications to route audio signals. A typical use case is highlighted in [Figure 20](#). The analog switch is supplied with 5 V and the control input is from a 5-V processor GPIO. In this case, there are no concerns related to excess power consumption.

### 9.2 Typical Application



**Figure 20. Typical Application Schematic**

#### 9.2.1 Design Requirements

In this application example, the device receives the control signal from a 5-V GPIO and common input from an Audio Power amplifier. The input is routed to either the Hands free set or the internal speaker depending upon the control signal.

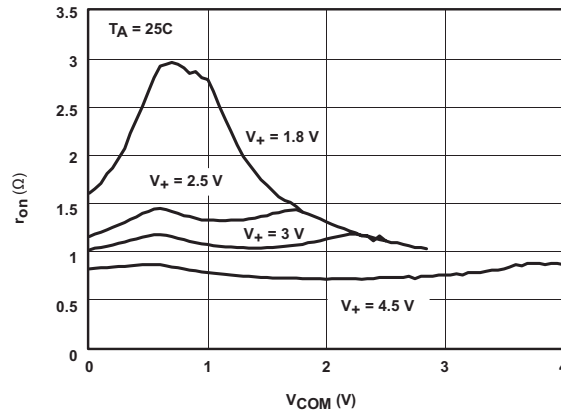
#### 9.2.2 Detailed Design Procedure

Since the control signal varies from 0 to 5 V (V<sub>dd</sub>), there's no excess current consumption. However, if the control signal comes from lower voltage GPIOs while the V<sub>+</sub> of TS5A3159 is connected to the battery whose voltage varies, it can lead to an excess current draw from the V<sub>+</sub> suppl pin. Such a scenario requires the use of an external voltage level translator such as the SN74LVC1T45. For more information see [Preventing Excess Current Consumption on Analog Switches](#), SCDA011.

**Typical Application (continued)**

**9.2.3 Application Curve**

The ON state resistance of the switch is a critical parameter to measure since it helps select the right switch for the application. The on state resistance versus the common voltage can be seen in [Figure 21](#).



**Figure 21.  $r_{on}$  vs  $V_{COM}$**

**10 Power Supply Recommendations**

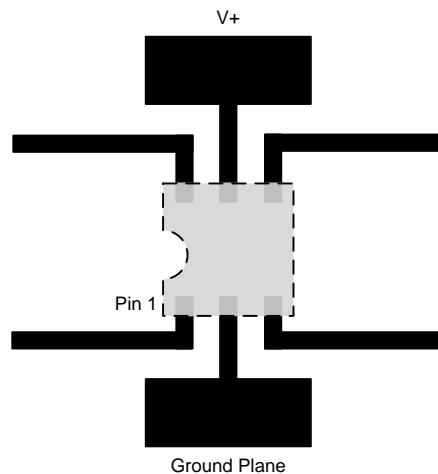
Most systems have a common 3.3 V or 5 V rail that can supply the  $V_+$  pin of this device. If this is not available, a Switch-Mode-Power-Supply (SMPS) or a Linear Dropout Regulator (LDO) can supply this device from a higher voltage rail. Proper decoupling of the supply rail is a must to avoid any spikes that may exceed the absolute ratings of the  $V_+$  pin of the device.

**11 Layout**

**11.1 Layout Guidelines**

TI recommends to keep signal lines as short as possible. Incorporation of microstrip or stripline techniques is also recommended when signal lines are greater than 1 inch in length. These traces must be designed with a characteristic impedance of either 50  $\Omega$  or 75  $\Omega$ , as required by the application. Do not place this device too close to high voltage switching components, as they may cause interference.

**11.2 Layout Example**



**Figure 22. Layout Example**

## 12 器件和文档支持

### 12.1 文档支持

#### 12.1.1 相关文档

相关文档如下：

《防止模拟开关电流消耗过大》（文献编号：SCDA011）

### 12.2 接收文档更新通知

如需接收文档更新通知，请访问 [www.ti.com.cn](http://www.ti.com.cn) 网站上的器件产品文件夹。点击右上角的提醒我 (Alert me) 注册后，即可每周定期收到已更改的产品信息。有关更改的详细信息，请查阅已修订文档中包含的修订历史记录。

### 12.3 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](http://e2e.ti.com), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 12.4 商标

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

### 12.5 静电放电警告



这些装置包含有限的内置 ESD 保护。存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

### 12.6 Glossary

**SLYZ022** — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。要获得这份数据表的浏览器版本，请查阅左侧的导航栏。

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TS5A3159QDBVRQ1	ACTIVE	SOT-23	DBV	6	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	UAAQ	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS5A3159QDBVRQ1	SOT-23	DBV	6	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

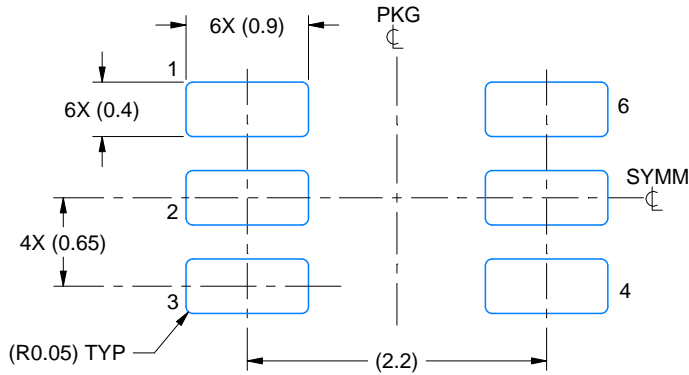


\*All dimensions are nominal

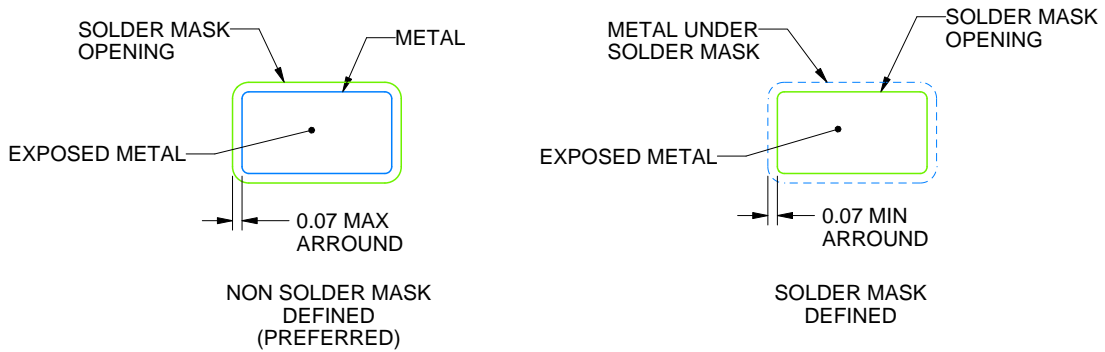
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS5A3159QDBVRQ1	SOT-23	DBV	6	3000	202.0	201.0	28.0







LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



SOLDER MASK DETAILS

4214835/D 11/2024

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

4214835/D 11/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.



# EXAMPLE BOARD LAYOUT

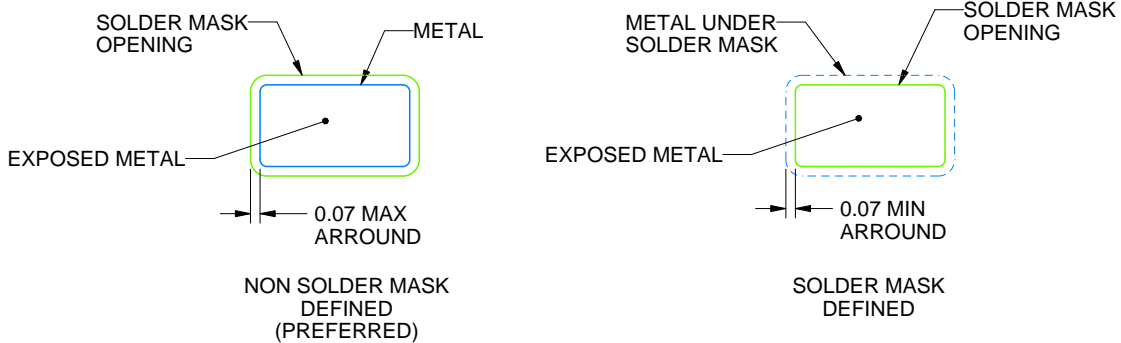
DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214840/G 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214840/G 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## 重要通知和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的相关应用。严禁以其他方式对这些资源进行复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
版权所有 © 2025，德州仪器 (TI) 公司